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(54) **ENCAPSULATION METHOD OF ENVIRONMENTALLY SENSITIVE ELECTRONIC ELEMENT**

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See application file for complete search history.

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(57) **ABSTRACT**

An encapsulation method of an environmentally sensitive electronic element is provided. A first substrate is provided, wherein at least one first alignment mark and a plurality of environmentally sensitive electronic elements are formed on the first substrate. A second substrate is provided, wherein at least one second alignment mark and a plurality of limiting cavities are formed on the second substrate. A plurality of cover lids is respectively disposed in the limiting cavities. An adhesive is formed on the cover lids. The first substrate and the second substrate are laminated together with the first alignment mark and the second alignment mark as reference, so that the environmentally sensitive electronic elements are sealed in the adhesive and located between the first substrate and the second substrate. The second substrate and the cover lids are separated from each other.

13 Claims, 9 Drawing Sheets